

Features

- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS Tested
- 100% ΔV_{ds} Tested
- Halogen-free; RoHS-compliant

Applications

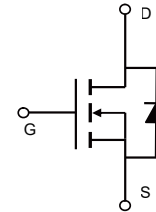
- Load Switch
- PWM Application
- Power Management

Product Summary

Parameters	Value	Unit
V_{DSS}	200	V
$V_{GS(th)}_{Typ}$	2.8	V
$I_D(@V_{GS}=10V)$	52	A
$R_{DS(ON)}_{Typ}(@V_{GS}=10V)$	49	m Ω



TO-220



Schematic

Ordering Information

Device	Marking	MSL	Form	Package	Tube(pcs)	Per Carton (pcs)
VSM52N20-TC	VSM52N20	N/A	Tube	TO-220	50	5000

Absolute Maximum Ratings (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Value	Unit
V _{DS}	Drain-to-Source Voltage		200	V
V _{GS}	Gate-to-Source Voltage		±30	V
I _D	Continuous Drain Current	T _C = 25°C	52	A
		T _C = 100°C	33	
I _{DM}	Pulsed Drain Current ⁽¹⁾		Refer to Fig.4	A
E _{AS}	Single Pulsed Avalanche Energy ⁽²⁾		1080	mJ
P _D	Power Dissipation	T _C = 25°C	208	W
		T _C = 100°C	83	
T _J , T _{STG}	Junction & Storage Temperature Range		-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽³⁾	69	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.6	

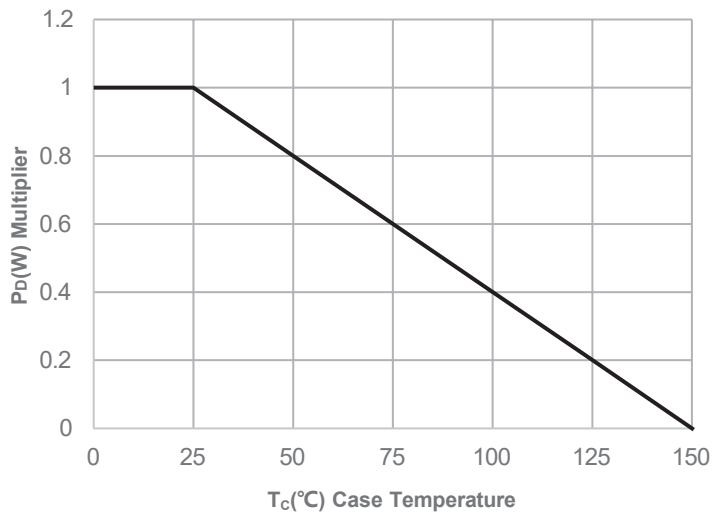
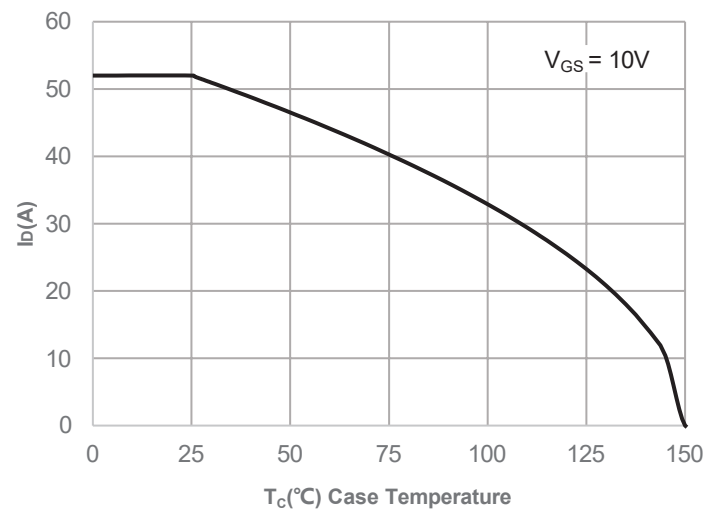
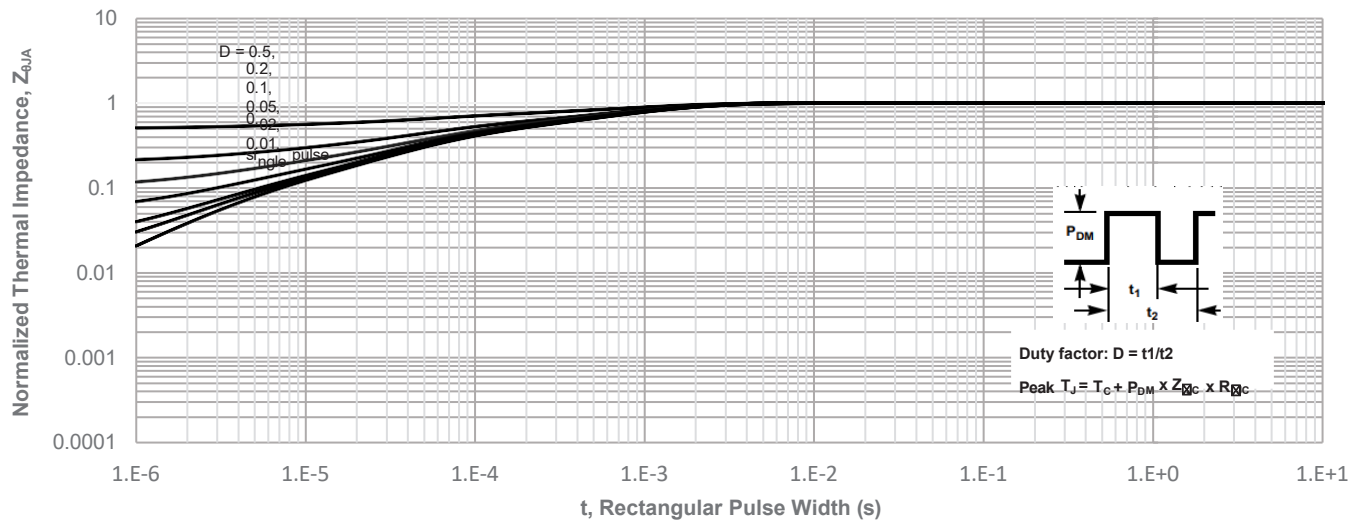
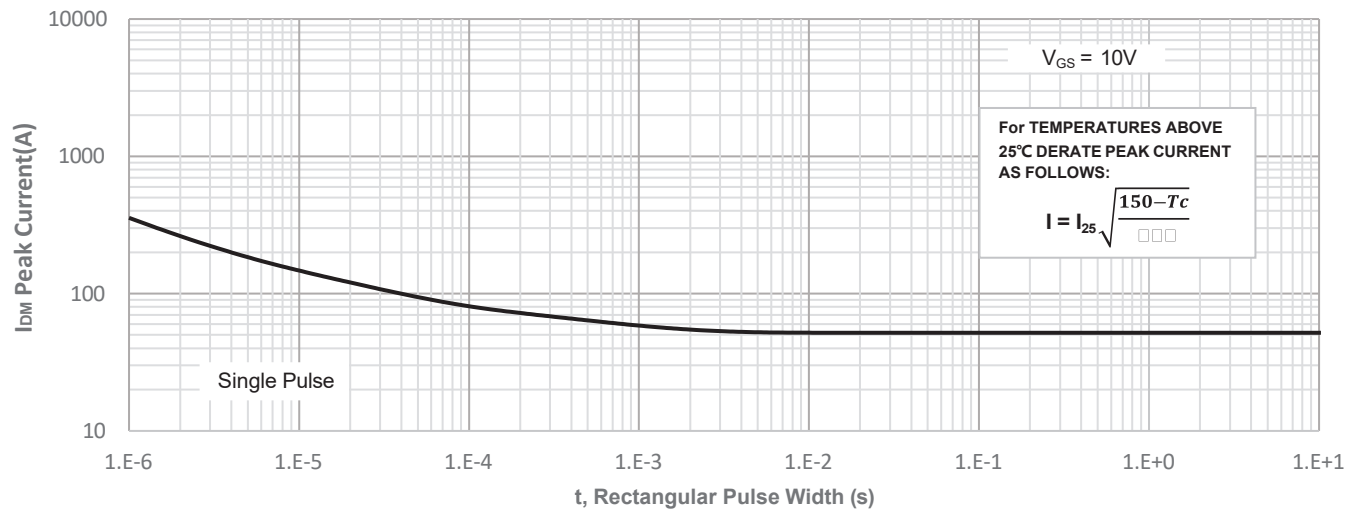
Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250 μA, V _{GS} = 0V	200	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =200V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±30V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	2.0	2.8	3.7	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽⁴⁾	V _{GS} = 10V, I _D =26A	-	49	64	mΩ
Dynamic Characteristics						
R _g	Gate Resistance	f = 1MHz	-	1.8	-	Ω
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 100V, f = 1MHz	1922	2691	3633	pF
C _{oss}	Output Capacitance		148	207	280	pF
C _{rss}	Reverse Transfer Capacitance		24	33	45	pF
Q _g	Total Gate Charge	V _{GS} = 0 to 10V V _{DS} = 100V, I _D = 52A	44	61	83	nC
Q _{gs}	Gate Source Charge		12	17	23	nC
Q _{gd}	Gate Drain("Miller") Charge		17	24	32	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} = 10V, V _{DD} = 100V I _D = 52A, R _{GEN} = 24 Ω	-	31	-	ns
t _r	Turn-On Rise Time		-	120	-	ns
t _{d(off)}	Turn-Off DelayTime		-	142	-	ns
t _f	Turn-Off Fall Time		-	107	-	ns
Body Diode Characteristics						
I _S	Maximum Continuous Body Diode Forward Current		-	-	52	A
I _{SM}	Maximum Pulsed Body Diode Forward Current		-	-	208	A
V _{SD}	Body Diode Forward Voltage	V _{GS} = 0V, I _S = 26A	-		1.2	V
t _{rr}	Body Diode Reverse Recovery Time	I _F = 52A, di/dt = 100A/us	115	161	218	ns
Q _{rr}	Body Diode Reverse Recovery Charge		-	1445	-	nC

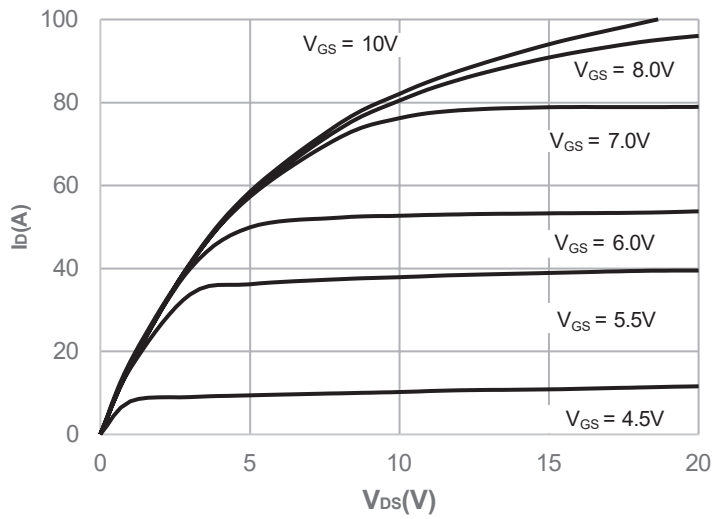
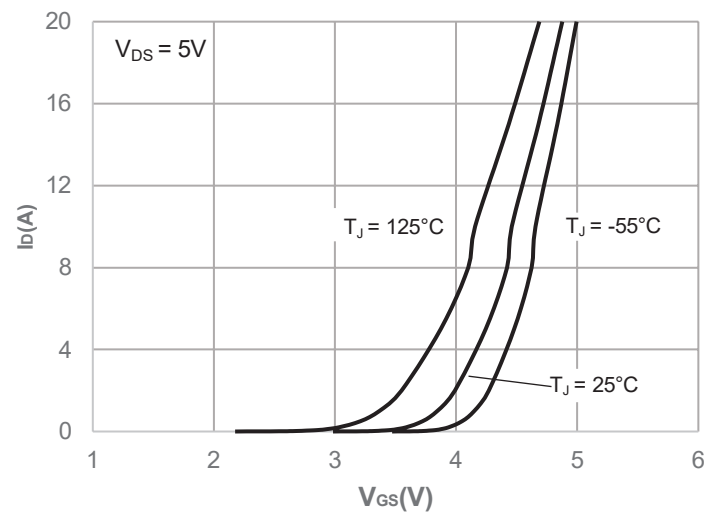
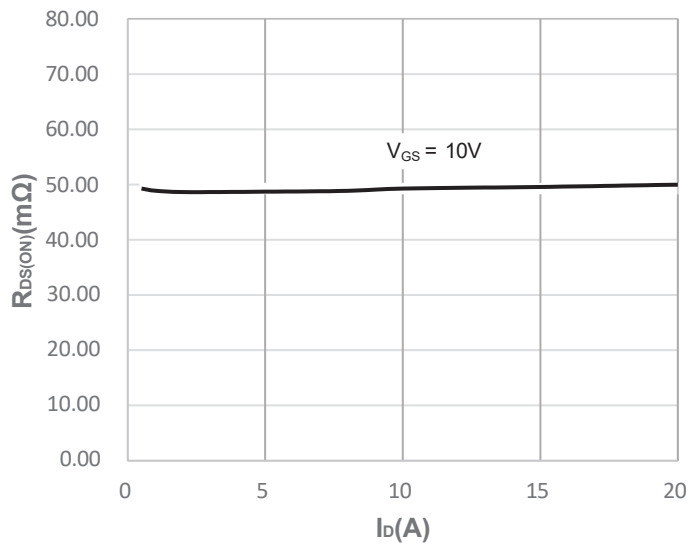
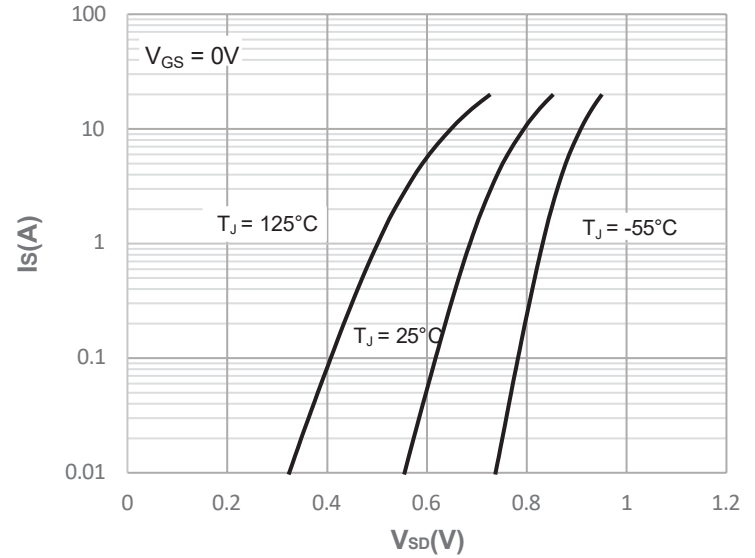
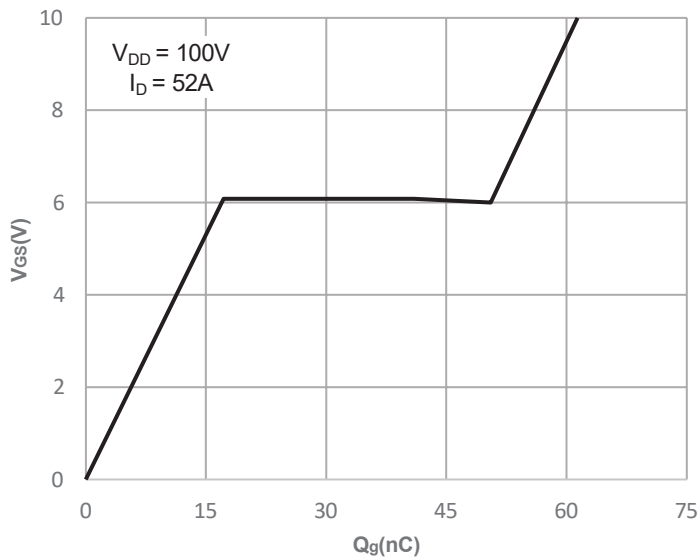
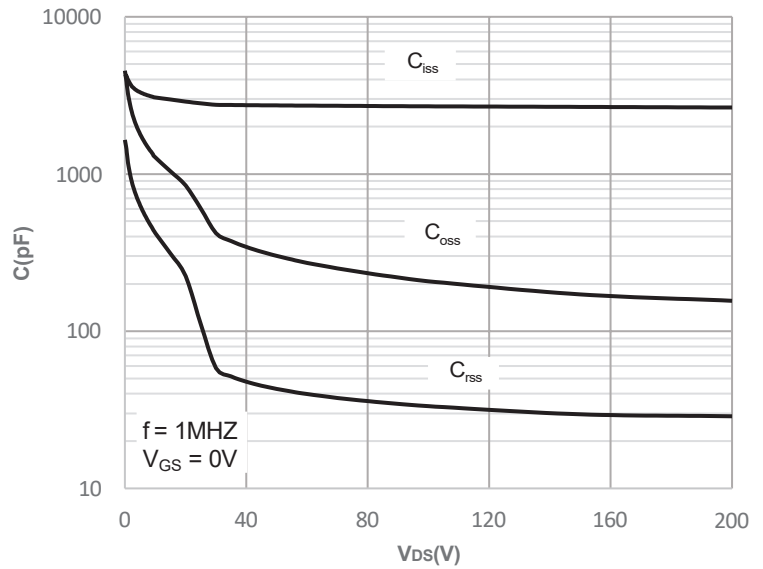
Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = 50\text{V}$, $V_G = 10\text{V}$, $R_G = 25\text{ohm}$, $L = 10\text{mH}$, $I_{AS} = 14.7\text{A}$, $V_{DD} = 0\text{V}$ during time in avalanche.
3. $R_{\theta JA}$ is measured with the device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
4. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Typical Performance Characteristics

Figure 1: Power De-rating

Figure 2: Current De-rating

Figure 3: Normalized Maximum Transient Thermal Impedance

Figure 4: Peak Current Capacity


Typical Performance Characteristics

Figure 5: Output Characteristics

Figure 6: Typical Transfer Characteristics

Figure 7: On-resistance vs. Drain Current

Figure 8: Body Diode Characteristics

Figure 9: Gate Charge Characteristics

Figure 10: Capacitance Characteristics


Typical Performance Characteristics

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

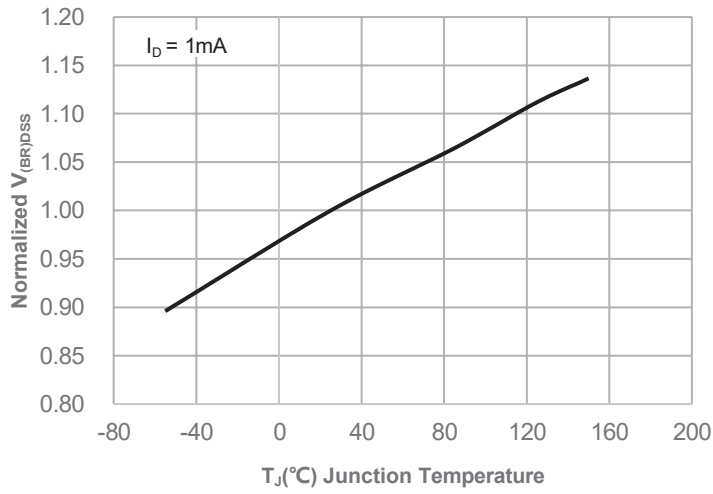


Figure 12: Normalized on Resistance vs. Junction Temperature

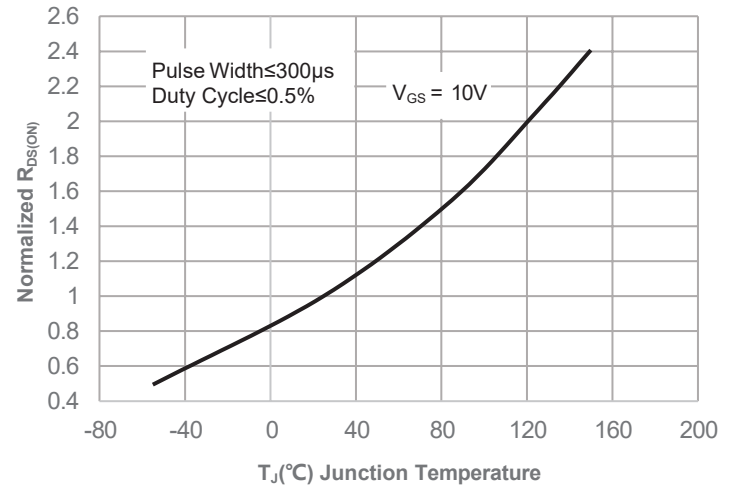


Figure 13: Normalized Threshold Voltage vs. Junction Temperature

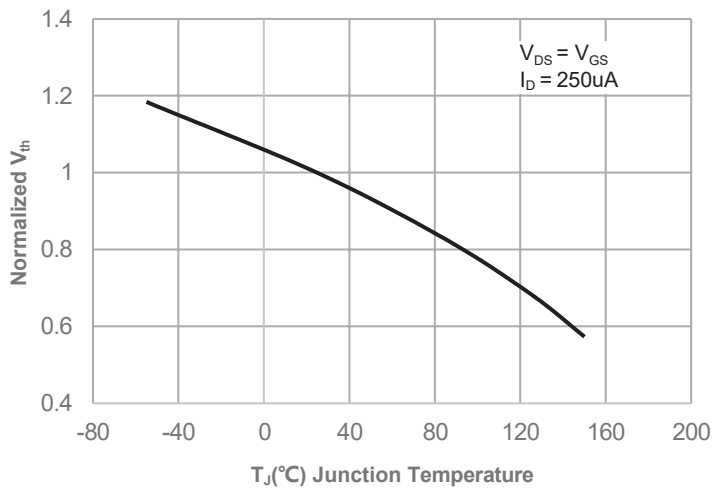


Figure 14: $R_{DS(ON)}$ vs. V_{GS}

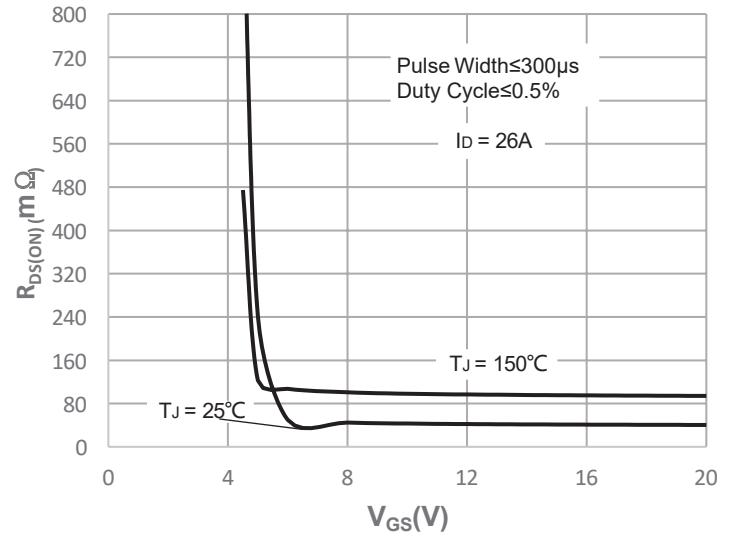
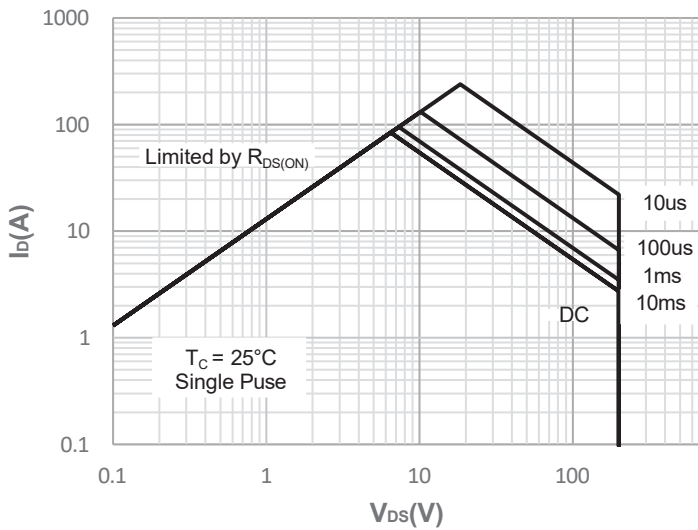


Figure 15: Maximum Safe Operating Area



Test Circuit

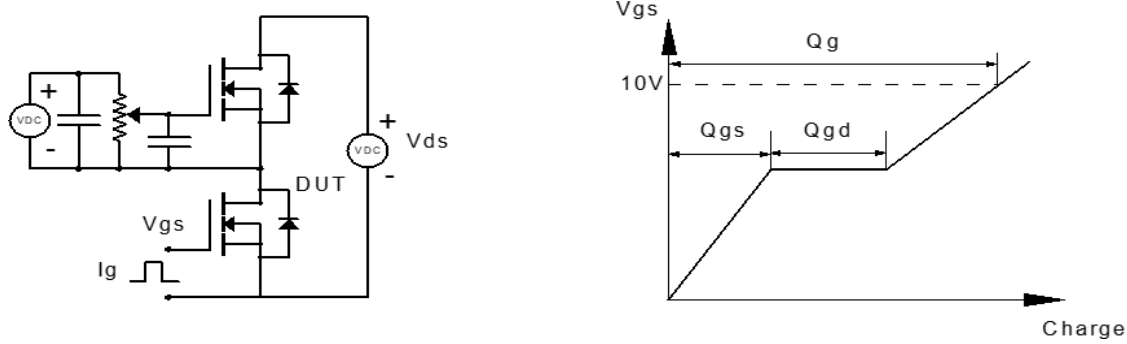


Figure 1: Gate Charge Test Circuit & Waveform

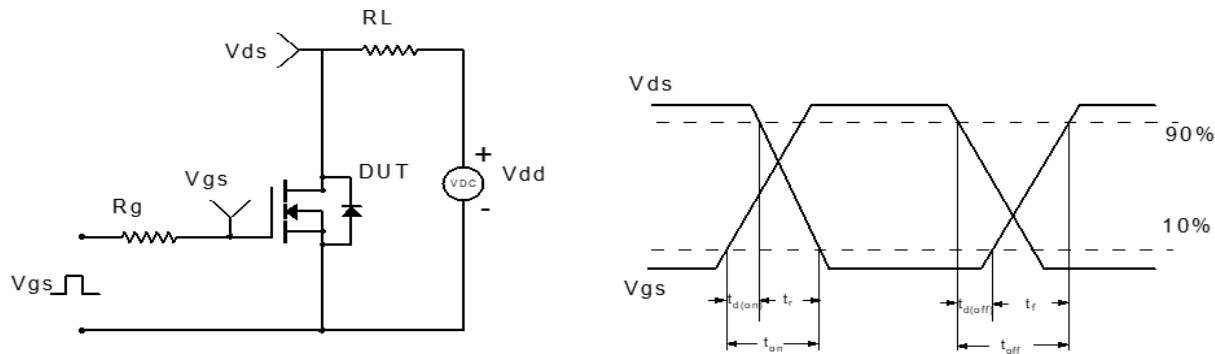


Figure 2: Resistive Switching Test Circuit & Waveform

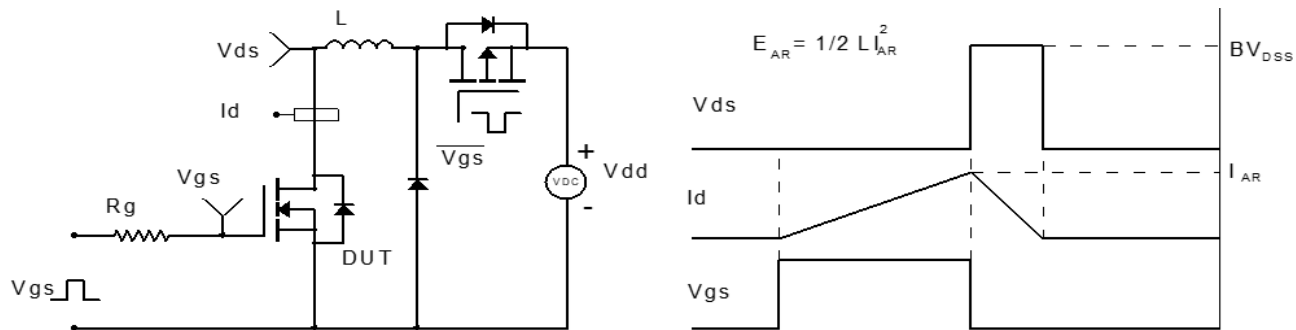


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

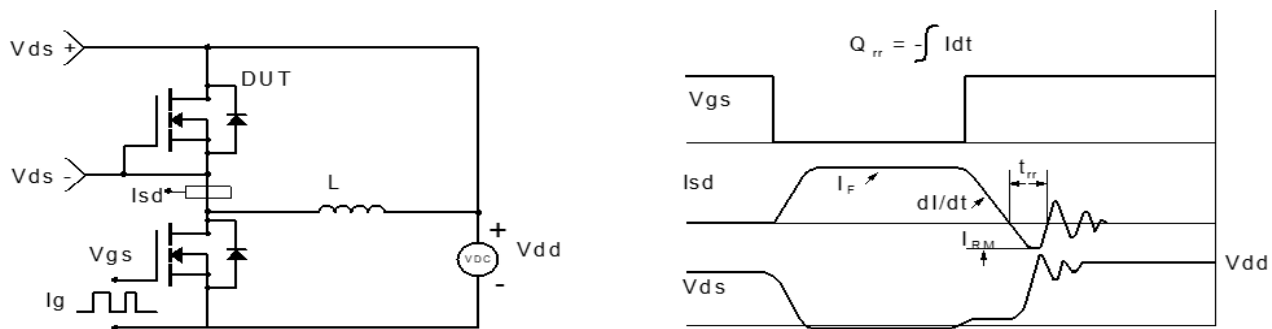


Figure 4: Diode Recovery Test Circuit & Waveform